Filename: PMP8622 REV_A_bom.xls Date: 06/13/2013

PMP8622 REV_A BOM

| COUNT | RefDes | Value | Description | Size | Part Number | Mfr |
|-------|--------|------------|---|--------------------|--------------------|---------------------|
| 1 | C1 | 18uF | Capacitor, Aluminum, 400V, 105C, 20% | 10mm x 20mm | EKXJ401ELL180MJ20S | Rubycon |
| 1 | C2 | 0.22 uF | Capacitor, Film, 275VAC, 20% | 0.689 x 0.217 | R46KI322050M2M | KEMET (Arcotronics) |
| 1 | C3 | 680uF | Capacitor, Aluminum, 16V, 105C, 20% | 10mm x 12.5mm | EKZM160ELL681MJC5S | Nippon Chemi-Con |
| 1 | C4 | 1000uF | Capacitor, Aluminum, 16V, 105C, 20% | 10mm x 16mm | EKZM160ELL102MJ16S | Nippon Chemi-Con |
| 1 | C5 | 1000 pF | Capacitor, 500Vac, Y5U ±20% | 10 mm | VY1102M35Y5UQ63V0 | Vishay |
| 1 | C6 | 10uF | Capacitor, Ceramic Chip, 25V, X5R, ±10% | 1206 | C3216X5R1E106K | TDK |
| 1 | D1 | 180V | Diode, TVS, 180-V, 400W | SMA | SMAJ180A | MDE |
| 1 | D2 | DF06S | Bridge Rectifier, 600V, 1A, SMD | DF-S | DF06S | Diodes |
| 1 | D3 | US1K | Diode, Rectifier, 1-A, 800V | SMA | US1K | Diodes |
| 1 | D4 | B380-13-F | Diode, Schottky, 3-A, 80-V | SMC | B380-13-F | Diodes |
| 1 | D5 | BAS21 | Diode, Switching, 200-mA, 250-V, | SOT23 | BAS21 | Vishay |
| 1 | D6 | DNP | Do not populate | D-PAK | N/A | N/A |
| 1 | F1 | 2A | Fuse, Time Lag, 2A, 250V | 0.335 inch | 3721200041 | Littlefuse |
| 1 | L3 | 1uH | Inductor, Power, 4.1 A, ±20% | 0.157 x 0.157 inch | XFL4020-102ML | Coilcraft |
| 2 | L1-2 | 1mH | Inductor, Filter Chocke, 0.42-A, 2.5-Ohm | 0.350 x 0.300 inch | 744743102 | Wuerth |
| 1 | Q1 | SPD03N60C3 | MOSFET, N-ch, 650-V, 3.2-A, 1.4-Ohm | DPAK | SPD03N60C3 | Infineon |
| 1 | R1 | 275V | Varistor, 275Vac | 0.472 x 0.213 inch | S10K275E2 | Epcos |
| 1 | R3 | 39 | Resistor, Chip 1/4 watt, ± 5% | 1206 | STD | STD |
| 1 | R5 | 3.3k | Resistor, Chip, 1/16W, 1% | 0603 | STD | STD |
| 1 | R6 | 100k | Resistor, Chip, 1/16W, 1% | 0603 | STD | STD |
| 1 | R7 | 10 | Resistor, Chip, 1/16W, 1% | 0603 | STD | STD |
| 1 | R8 | 1k | Resistor, Chip, 1/16W, 1% | 0603 | STD | STD |
| 1 | R9 | 28.7k | Resistor, Chip, 1/16W, 1% | 0603 | STD | STD |
| 1 | R10 | 1.8 | Resistor, Chip 1/4 watt, ±1% | 1206 | STD | STD |
| 1 | R11 | 0 | Resistor, Chip, 1/16W, 1% | 0603 | STD | STD |
| 2 | R2 R4 | 10k | Resistor, Chip 1/4 watt, ± 5% | 1206 | STD | STD |
| 1 | T1 | 2.2 mH | Transformer, Flyback, 12W | 22.2mm x 25mm | 750817133 | Wuerth |
| 1 | TP3 | 5000 | Test Point, Red, Thru Hole Color Keyed | 0.100 x 0.100 inch | 5000 | Keystone |
| 1 | TP4 | 5001 | Test Point, Black, Thru Hole Color Keyed | 0.100 x 0.100 inch | 5001 | Keystone |
| 2 | TP1-2 | 5012 | Test Point, White, Thru Hole | 0.125 x 0.125 inch | 5012 | Keystone |
| 1 | U1 | UCC28711D | IC, Constant Voltage, Constant Current PWM With Primary Side Regulation | SO-8 | UCC28711D | TI |

Notes: 1. These assemblies are ESD sensitive, ESD precautions shall be observed.

2. These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.

4. Ref designators marked with an asterisk ('**') cannot be substituted.

All other components can be substituted with equivalent MFG's components.

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